TOSHIBA Field Effect Transistor Silicon N Channel MOS Type

# SSM3K106TU

#### **High-Speed Switching Applications**

• 4 V drive

• Low ON-resistance:  $R_{on} = 530 \text{ m}\Omega \text{ (max) (@V_{GS} = 4 V)}$ 

 $R_{on} = 310 \text{ m}\Omega \text{ (max) (@V_{GS} = 10 V)}$ 

## Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit	
Drain-source voltage		V <sub>DS</sub>	20	V	
Gate-source voltage		V <sub>GSS</sub>	± 20	V	
Drain current	DC	I <sub>D</sub>	1.2	Α	
	Pulse	I <sub>DP</sub>	2.4		
Drain power dissipation		P <sub>D (Note 1)</sub>	800	mW	
		P <sub>D</sub> (Note 2)	500	11100	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	<b>−55~150</b>	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

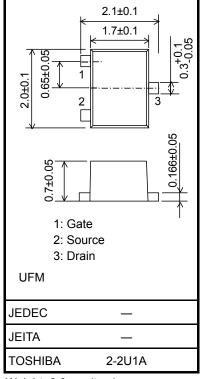
Note 1: Mounted on a ceramic board.

 $(25.4 \text{ mm} \times 25.4 \text{ mm} \times 0.8 \text{ mm}, \text{ Cu Pad: } 645 \text{ mm}^2)$ 

Note 2: Mounted on an FR4 board.

(25.4 mm  $\times$  25.4 mm  $\times$  1.6 mm, Cu Pad: 645 mm<sup>2</sup>)

# Unit: mm



Weight: 6.6 mg (typ.)

#### **Electrical Characteristics (Ta = 25°C)**

Charact	teristic	Symbol	Test Conditions	Min	Тур.	Max	Unit
Drain-source break	down voltage	V (BR) DSS	$I_D = 1 \text{ mA}, V_{GS} = 0$		_	_	V
Drain cutoff current	t	I <sub>DSS</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0	_	_	1	μА
Gate leakage curre	ent	I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0$	_	_	±1	μА
Gate threshold volt	age	V <sub>th</sub>	$V_{DS} = 5 \text{ V}, I_D = 0.1 \text{ mA}$	1.1	_	2.3	V
Forward transfer ac	dmittance	Y <sub>fs</sub>	$V_{DS} = 5 \text{ V}, I_D = 0.6 \text{ A}$ (Note	3) 0.58	1.16	_	S
Drain-source ON-resistance		R <sub>DS</sub> (ON)	I <sub>D</sub> = 0.6 A, V <sub>GS</sub> = 10 V (Note	e 3) —	230	310	mΩ
			I <sub>D</sub> = 0.6 A, V <sub>GS</sub> = 4 V (Note	e 3) —	390	530	
Input capacitance		C <sub>iss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		36	_	pF
Output capacitance	9	Coss	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0, f = 1 MHz	_	30	_	pF
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0, f = 1 MHz		10	_	pF
Switching time	Turn-on time	t <sub>on</sub>	$V_{DD} = 10 \text{ V}, I_D = 0.6 \text{ A},$ $V_{GS} = 0~4 \text{ V}, R_G = 10 \Omega$	_	21	_	ns
	Turn-off time	t <sub>off</sub>		_	8	_	
Drain-source forwa	ird voltage	V <sub>DSF</sub>	$I_D = -1.2 \text{ A}, V_{GS} = 0 \text{ V}$ (Not	e 3)	-1.0	-1.4	V

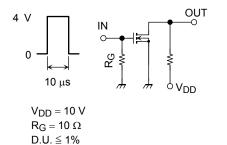
Note 3: Pulse test

#### **Switching Time Test Circuit**

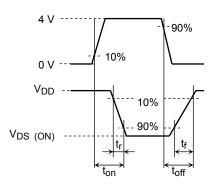
 $V_{IN}\text{: }t_{r}\text{, }t_{f}<5\text{ ns}$  Common Source  $Ta=25^{\circ}C$ 

#### (a) Test Circuit

#### (b) V<sub>IN</sub>

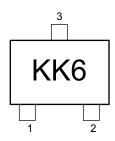


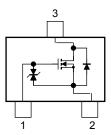




#### Marking

## **Equivalent Circuit (top view)**





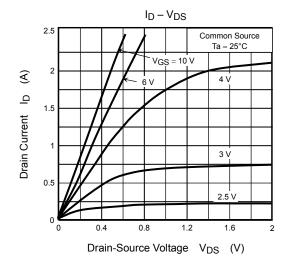
#### Note

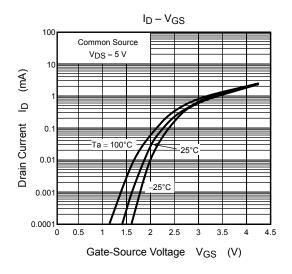
 $V_{th}$  can be expressed as the voltage between gate and source when the low operating current value is  $I_D$  = 0.1 mA for this product. For normal switching operation,  $V_{GS}$  (on) requires a higher voltage than  $V_{th}$ , and  $V_{GS}$  (off) requires a lower voltage than  $V_{th}$ . (The relationship can be established as follows:  $V_{GS}$  (off) <  $V_{th}$  <  $V_{GS}$  (on).)

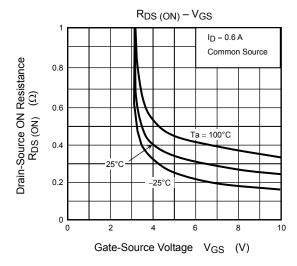
Take this into consideration when using the device.

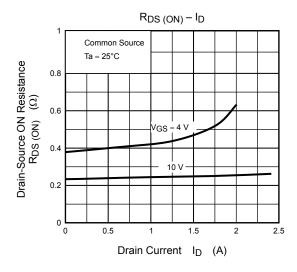
## **Handling Precaution**

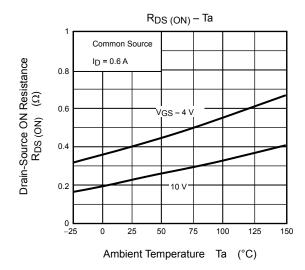
When handling individual devices that are not yet mounted on a circuit board, be sure that the environment is protected against electrostatic discharge. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

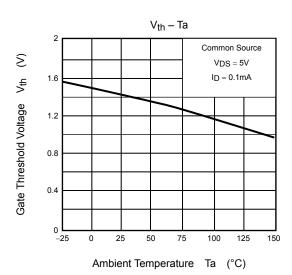


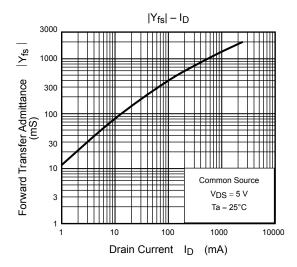


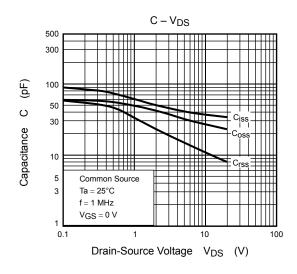


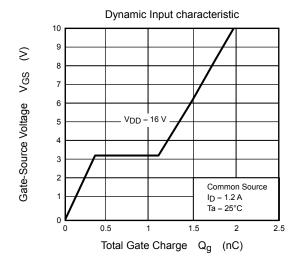


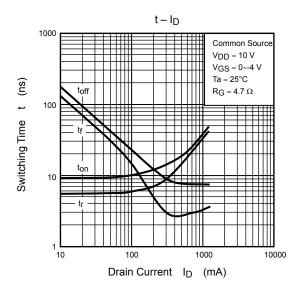


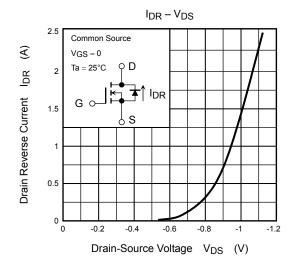


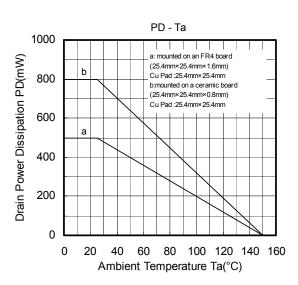


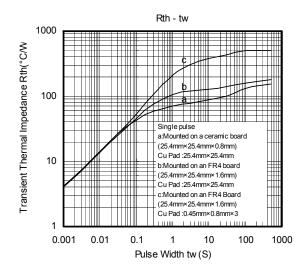












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